

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2	"20040201102"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/02 11:05
S2	2	"20020043723"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/02 11:08
S3	2	("6538326").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/02 11:08
S4	1	"5597737".PN.	USPAT; USOCR	OR	ON	2005/06/02 11:13
S5	1	"6229221".PN.	USPAT; USOCR	OR	ON	2005/06/02 11:13
S6	1	"6127715".PN.	USPAT; USOCR	OR	ON	2005/06/02 11:13
S7	1	"5989991".PN.	USPAT; USOCR	OR	ON	2005/06/02 11:13
S8	1	"5597737".PN.	USPAT; USOCR	OR	ON	2005/06/02 11:13
S9	6838	@ad<="20040408" and (257/758). ccls. or (257/759).ccls. or (257/780).ccls. or (257/784).ccls. or (257/E23.151).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 11:20
S10	33	@ad<="20040408" and 'bonding pad' and 'first wire' and 'second wire' and 'semiconductor element'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/02 12:00
S11	2	("5989991").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/02 11:59
S13	1369	@ad<="20040408" and 'bonding pad' and 'adhesion' and 'semiconductor' with 'structure'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/02 12:02
S15	682	@ad<="20040408" and 'bonding pad' and 'adhesion' and 'semiconductor' with 'structure' and 'wiring'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/02 12:02

S16	298	@ad<="20040408" and 'bonding pad' and 'adhesion' and 'semiconductor device' and 'wiring layer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/02 12:22
S17	1	"6399997".PN.	USPAT; USOCR	OR	ON	2005/06/02 12:12
S18	1	"6392300".PN.	USPAT; USOCR	OR	ON	2005/06/02 12:12
S19	1	"6303459".PN.	USPAT; USOCR	OR	ON	2005/06/02 12:13
S20	1	"6291331".PN.	USPAT; USOCR	OR	ON	2005/06/02 12:13
S21	1	"6232662".PN.	USPAT; USOCR	OR	ON	2005/06/02 12:14
S22	1	"6124198".PN.	USPAT; USOCR	OR	ON	2005/06/02 12:14
S23	1	"5554940".PN.	USPAT; USOCR	OR	ON	2005/06/02 12:15
S24	1	"5554940".PN.	USPAT; USOCR	OR	ON	2005/06/02 12:15
S25	30	@ad<="20040408" and 'bonding pad' and 'adhesion' and 'semiconductor device' and 'Multilayer wiring structure'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 11:25
S26	693	@ad<="20040408" and (257/459). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/02 12:37
S28	2360	@ad<="20040408" and (438/612). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/02 12:39
S29	1963	@ad<="20040408" and (438/614). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/02 12:39
S30	1063	@ad<="20040408" and (438/618). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/02 12:39
S31	1761	@ad<="20040408" and (257/786). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 11:20

S32	1909	@ad<="20040408" and (257/737). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 11:20
S33	382	@ad<="20040408" and (257/772). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 11:21
S34	2088	@ad<="20040408" and (257/773). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 11:21
S35	3267	@ad<="20040408" and (257/758). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 11:24
S36	545	@ad<="20040408" and (257/759). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 11:21
S37	783	@ad<="20040408" and (257/760). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 11:27
S38	1403	@ad<="20040408" and (438/118). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 11:23
S39	2394	@ad<="20040408" and (438/622). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 11:23
S40	342	@ad<="20040408" and (257/758). ccls. and 'bonding pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 11:24
S41	684	@ad<="20040408" and 'bonding pad' and 'semiconductor device' and 'Multilayer' with ('wiring' or 'wire' or 'layer')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 12:04
S42	5	@ad<="20040408" and 'bonding pad' and 'semiconductor device' and 'Multilayer' with ('wiring' or 'wire' or 'layer') and 'inorganic dielectric'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 11:28

S43	62	@ad<="20040408" and (257/760). ccls. and 'bonding pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 12:16
S44	14	@ad<="20040408" and 'bump' and 'semiconductor device' and 'Multilayer' with ('wiring' or 'wire' or 'layer') and 'inorganic dielectric'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 11:28
S45	1	"6090633".PN.	USPAT; USOCR	OR	ON	2005/11/30 11:38
S46	1	"6078100".PN.	USPAT; USOCR	OR	ON	2005/11/30 11:38
S47	247	@ad<="20040408" and 'bonding pad' and 'semiconductor device' and 'Multilayer' with ('wiring' or 'wire' or 'layer') and 'bump'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 11:47
S49	612	@ad<="20040408" and 'semiconductor device' same ('wiring' or 'wire' or 'layer') same 'pad' same 'solder bump'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 11:48
S50	95	@ad<="20040408" and 'semiconductor device' same ('wiring' or 'wire' or 'layer') same 'bonding pad' same 'solder bump'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 11:48
S51	153	@ad<="20040408" and 'semiconductor device' same ('wiring' or 'wire' or 'layer') same ('bonding' or 'contact') adj1 'pad' same 'solder bump'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 11:48
S52	313	@ad<="20040408" and 'wire bond pad' same 'semiconductor device'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 12:04
S53	236	@ad<="20040408" and 'wire bond pad' with 'semiconductor device'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 12:04
S54	1	"6798035".PN.	USPAT; USOCR	OR	ON	2005/11/30 12:06
S55	1	"6625882".PN.	USPAT; USOCR	OR	ON	2005/11/30 12:06
S56	1	"6614091".PN.	USPAT; USOCR	OR	ON	2005/11/30 12:07
S57	1	"6399997".PN.	USPAT; USOCR	OR	ON	2005/11/30 12:07
S58	1	"6392300".PN.	USPAT; USOCR	OR	ON	2005/11/30 12:07

S59	1	"6383916".PN.	USPAT; USOCR	OR	ON	2005/11/30 12:07
S60	1	"6372661".PN.	USPAT; USOCR	OR	ON	2005/11/30 12:07
S61	1	"6291331".PN.	USPAT; USOCR	OR	ON	2005/11/30 12:08
S62	1	"6232662".PN.	USPAT; USOCR	OR	ON	2005/11/30 12:08
S63	2	@ad<="20040408" and (257/760). ccls. and 'wire bond pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 12:17
S64	4	@ad<="20040408" and (257/759). ccls. and 'wire bond pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 12:17
S65	33	@ad<="20040408" and (257/758). ccls. and 'wire bond pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 12:19
S66	24	@ad<="20040408" and (257/760). ccls. and 'bond pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 12:17
S67	26	@ad<="20040408" and (257/759). ccls. and 'bond pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 12:19
S68	54	@ad<="20040408" and (257/759). ccls. and 'bonding pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 12:19
S69	342	@ad<="20040408" and (257/758). ccls. and 'bonding pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 12:19
S70	62	@ad<="20040408" and (257/760). ccls. and 'bonding pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 12:19